

# DIANHYDRIDES & IMIDES 1040A

## DESCRIPTION

Transparent, high flow polyetherimide.

## TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL</b>			
Tensile Stress, yld, Type I, 5 mm/min	97	MPa	ASTM D638
Tensile Strain, brk, Type I, 5 mm/min	10	%	ASTM D638
Tensile Modulus, 5 mm/min	3440	MPa	ASTM D638
Flexural Stress, yld, 2.6 mm/min, 100 mm span	159	MPa	ASTM D790
Flexural Modulus, 2.6 mm/min, 100 mm span	3510	MPa	ASTM D790
<b>IMPACT</b>			
Izod Impact, unnotched, 23°C	470	J/m	ASTM D4812
Izod Impact, notched, 23°C	21	J/m	ASTM D256
Gardner, 23°C	8	J	ASTM D3029
<b>THERMAL</b>			
HDT, 1.82 MPa, 6.4 mm, unannealed	196	°C	ASTM D648
<b>PHYSICAL</b>			
Specific Gravity	1.27	-	ASTM D792
Mold Shrinkage, flow, 3.2 mm	0.5 – 0.7	%	SABIC method
Melt Flow Rate, 295°C/6.6 kgf	6.6	g/10 min	ASTM D1238

## ADDITIONAL PRODUCT NOTES

No PFAS intentionally added: The grade listed in this document does not contain PFAS intentionally added during Seller's manufacturing process and is not expected to contain unintentional PFAS impurities. Each user is responsible for evaluating the presence of unintentional PFAS impurities.

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